

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc2911cddb-2#trmpbf

(Engineering Calculation)

DFN 3mm X 2mm Exp. Pad

(printed on: 2020-07-11 17:00:52)

**TOTAL MASS (g) : 0.013526**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000684	1000000	50570.75		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.004211	974800.0625	311335.40625		
		Iron (Fe)	7439-89-6	0.000102	23500	7541.25146484		
		Phosphorus (P)	7723-14-0	0.000004	850	295.73538208		
		Zinc (Zn)	7440-66-6	0.000004	850	295.73538208		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.004321</b>	<b>1000000</b>	<b>319468.125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000185	1000000	13648.6669922		
		<b>External Plating Total:</b>				<b>0.000185</b>	<b>1000000</b>	<b>13648.6669922</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000103	1000000	7615.18554688		
<b>Internal Plating Total:</b>				<b>0.000103</b>	<b>1000000</b>	<b>7615.18554688</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000200	800000	14786.7675781		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000050	200000	3696.69189453		
<b>Die Attach Total:</b>				<b>0.000250</b>	<b>1000000</b>	<b>18483.4609375</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001034	130000	76447.5859375		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.006837	860000	505485.65625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000080	10000	5914.70703125		
		<b>Encapsulation Total:</b>				<b>0.007951</b>	<b>1000000</b>	<b>587847.9375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000032	1000000	2365.88305664		
					<b>TOTAL MASS (g) :</b>	<b>0.013526</b>		